

PTVS Overvoltage Protectors - User Solder Profile

Axial Thru-Hole Mount Packages - Pb Free Soldering

Packages are designed to be mounted above Printed Wiring Boards with leads protruding through mounting holes in the Printed Wiring Board.

Under these solder mounting conditions, the component body is heated by conduction from the molten solder via the component leads. The package body is shielded from direct bottom side heating by the Printed Wiring Board itself.

Components are tested during qualification to ensure they are robust when terminations are exposed to Pb-Free wave soldering conditions specified in JEDEC Standard JESD22-B106

Solder Temperature 270 +/- 5 °C Exposure Time 7 +2/-0 seconds

Pb Free Reflow Soldering of Axial Packages

In some applications it may be more convenient for the user to consider soldering parts using a surface mount reflow solder profile.

Under these conditions, the whole of the package is subjected to direct heating from the reflow oven.

Customer wishing to solder components by this method should request assurance from Bourns about the suitability of their solder profile.

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